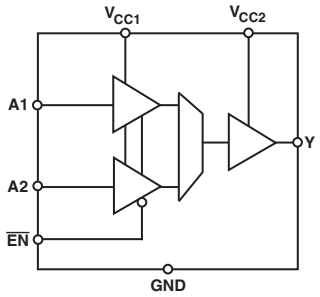
Low Voltage 2-1 Mux, Level Translator

ADG3232*

FEATURES
Operates from 1.65 V to 3.6 V Supply Rails
Unidirectional Signal Path, Bidirectional Level Translation
Tiny 8-Lead SOT-23 Package
Short Circuit Protection
LVTTL/CMOS Compatible Inputs

APPLICATIONS
Level Translation
Low Voltage ASIC Translation
Low Voltage Clock Switching
Serial Interface Translation

FUNCTIONAL BLOCK DIAGRAM



GENERAL DESCRIPTION

The ADG3232 is a level translator 2-1 mux designed on a submicron process and operates from supplies as low as 1.65 V. The device is guaranteed for operation over the supply range 1.65 V to 3.6 V. It operates from two supply voltages, allowing bidirectional level translation, i.e., it translates low voltages to higher voltages and vice versa. The signal path is unidirectional, meaning data may flow only from A to Y.

This type of device may be used in applications requiring communication between devices operating from different supply levels.

The level translator mux is packaged in one of the smallest footprints available for its pin count. The 8-lead SOT-23 package requires only 8.26 mm × 8.26 mm of board space.

PRODUCT HIGHLIGHTS

1. Bidirectional level translation matches any voltage level from 1.65 V to 3.6 V.
2. The device offers high performance and is fully guaranteed across the supply range.
3. Short circuit protection.
4. Tiny SOT-23 package.

Table I. Truth Table

$\overline{EN}$	Function
L	A1–Y
H	A2–Y

*Patent Pending

REV. 0

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ADG3232–SPECIFICATIONS[1] (V_{CC1} = V_{CC2} = 1.65 V to 3.6 V, GND = 0 V. All specifications T_{MIN} to T_{MAX}, unless otherwise noted.)

Parameter	Symbol	Conditions	Min	Typ[2]	Max	Unit
LOGIC INPUTS/OUTPUTS[3]						
Input High Voltage[4]	V_{IH}	V_{CC1} = 3.0 V to 3.6 V	1.35			V
	V_{IH}	V_{CC1} = 2.3 V to 2.7 V	1.35			V
	V_{IH}	V_{CC1} = 1.65 V to 1.95 V	0.65 V_{CC}			V
Input Low Voltage[4]	V_{IL}	V_{CC1} = 3.0 V to 3.6 V			0.80	V
	V_{IL}	V_{CC1} = 2.3 V to 2.7 V			0.70	V
	V_{IL}	V_{CC1} = 1.65 V to 1.95 V			0.35 V_{CC}	V
Output High Voltage	V_{OH}	I_{OH} = –100 mA, V_{CC2} = 3.0 V to 3.6 V	2.4			V
		V_{CC2} = 2.3 V to 2.7 V	2.0			V
		V_{CC2} = 1.65 V to 1.95 V	V_{CC} – 0.45			V
		I_{OH} = –4 mA, V_{CC2} = 2.3 V to 2.7 V	2.0			V
		V_{CC2} = 1.65 V to 1.95 V	V_{CC} – 0.45			V
		I_{OH} = –8 mA, V_{CC2} = 3.0 V to 3.6 V	2.4			V
Output Low Voltage	V_{OL}	I_{OH} = +100 mA, V_{CC2} = 3.0 V to 3.6 V			0.40	V
		V_{CC2} = 2.3 V to 2.7 V			0.40	V
		V_{CC2} = 1.65 V to 1.95 V			0.45	V
		I_{OH} = +4 mA, V_{CC2} = 2.3 V to 2.7 V			0.40	V
		V_{CC2} = 1.65 V to 1.95 V			0.45	V
		I_{OH} = +8 mA, V_{CC2} = 3.0 V to 3.6 V			0.40	V
SWITCHING CHARACTERISTICS[4, 5]						
Propagation Delay, t_{PD}						
A1 to Y	t_{PHL}, t_{PLH}	3.3 V ± 0.3 V, C_L = 30 pF, V_T = V_{CC}/2		4	6.5	ns
A2 to Y	t_{PHL}, t_{PLH}	3.3 V ± 0.3 V, C_L = 30 pF, V_T = V_{CC}/2		3.5	5.4	ns
A1 to Y	t_{PHL}, t_{PLH}	2.5 V ± 0.2 V, C_L = 30 pF, V_T = V_{CC}/2		5	7.2	ns
A2 to Y	t_{PHL}, t_{PLH}	2.5 V ± 0.2 V, C_L = 30 pF, V_T = V_{CC}/2		4.5	6.5	ns
A1 to Y	t_{PHL}, t_{PLH}	1.8 V ± 0.15 V, C_L = 30 pF, V_T = V_{CC}/2		6.5	10.25	ns
A2 to Y	t_{PHL}, t_{PLH}	1.8 V ± 0.15 V, C_L = 30 pF, V_T = V_{CC}/2		6.5	10	ns
ENABLE Time $\overline{EN}$ to Y	$t_{\overline{EN}}$	3.3 V ± 0.3 V, C_L = 30 pF, V_T = V_{CC}/2		4.5	6.5	ns
DISABLE Time $\overline{EN}$ to Y	t_{DIS}	3.3 V ± 0.3 V, C_L = 30 pF, V_T = V_{CC}/2		4	6.5	ns
ENABLE Time $\overline{EN}$ to Y	$t_{\overline{EN}}$	2.5 V ± 0.2 V, C_L = 30 pF, V_T = V_{CC}/2		5	7.7	ns
DISABLE Time $\overline{EN}$ to Y	t_{DIS}	2.5 V ± 0.2 V, C_L = 30 pF, V_T = V_{CC}/2		4.8	7.2	ns
ENABLE Time $\overline{EN}$ to Y	$t_{\overline{EN}}$	1.8 V ± 0.15 V, C_L = 30 pF, V_T = V_{CC}/2		7	12	ns
DISABLE Time $\overline{EN}$ to Y	t_{DIS}	1.8 V ± 0.15 V, C_L = 30 pF, V_T = V_{CC}/2		6.5	10.5	ns
Input Leakage Current	I_I	0 ≤ V_{IN} ≤ 3.6 V			±1	µA
Output Leakage Current	I_O	0 ≤ V_{IN} ≤ 3.6 V			±1	µA
POWER REQUIREMENTS						
Power Supply Voltages	V_{CC1}		1.65		3.6	V
	V_{CC2}		1.65		3.6	V
Quiescent Power Supply Current						
	I_{CC1}	Digital Inputs = 0 V or V_{CC}			2	µA
	I_{CC2}	Digital Inputs = 0 V or V_{CC}			2	µA
Increase in I_{CC} per Input	ΔI_{CC12}	V_{CC} = 3.6 V, One Input at 3.0 V; Others at V_{CC} or GND			0.75	µA

NOTES

[1] Temperature range is as follows: B Version, –40°C to +85°C.

[2] All typical values are at V_{CC1} = V_{CC2}, T_A = 25°C, unless otherwise stated.

[3] V_{IL} and V_{IH} levels are specified with respect to V_{CC1}; V_{OH} and V_{OL} levels are with respect to V_{CC2}.

[4] Guaranteed by design, not subject to production test.

[5] See Test Circuits and Waveforms.

Specifications subject to change without notice.

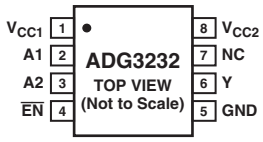
ABSOLUTE MAXIMUM RATINGS*

(T_A = 25°C, unless otherwise noted.)

V_{CC} to GND . . . . . –0.3 V to +4.6 V
A1, $\overline{EN}$ Input Voltage . . . . . –0.3 V to +4.6 V
A2 . . . . . –0.3 V to V_{CC1} to +0.3 V
DC Output Current . . . . . 25 mA
Operating Temperature Range
Industrial (B Version) . . . . . –40°C to +85°C
Storage Temperature Range . . . . . –65°C to +150°C
Junction Temperature . . . . . 150°C
8-Lead SOT-23,
θ_{JA} Thermal Impedance . . . . . 211°C/W
Lead Temperature, Soldering (10 seconds) . . . . . 300°C
IR Reflow, Peak Temperature (<20 seconds) . . . . . 235°C

*Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those listed in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Only one absolute maximum rating may be applied at any one time.

PIN CONFIGURATION



ORDERING GUIDE

Model	Temperature Range	Package Description	Branding	Package Option
ADG3232BRJ-REEL	–40°C to +85°C	SOT-23	W3B	RJ-8
ADG3232BRJ-REEL7	–40°C to +85°C	SOT-23	W3B	RJ-8

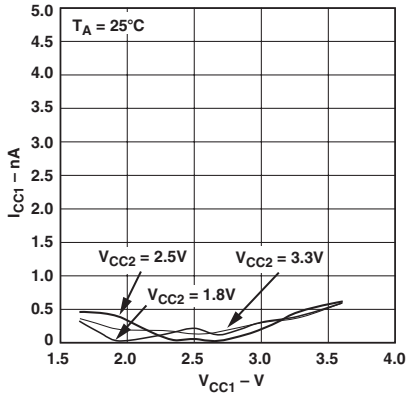
PIN FUNCTION DESCRIPTIONS

Pin	Mnemonic	Description
1	V_{CC1}	Supply Voltage 1, can be any supply voltage from 1.65 V to 3.6 V.
2	A1	Input Referred to V_{CC1}.
3	A2	Input Referred to V_{CC2}.
4	$\overline{EN}$	Active low device enable. When low, bypass mode is enabled; when high, the device is in normal mode.
5	GND	Device Ground Pin.
6	Y	Output Referred to V_{CC2}.
7	NC	Not Internally Connected.
8	V_{CC2}	Supply Voltage 2, can be any supply voltage from 1.65 V to 3.6 V.

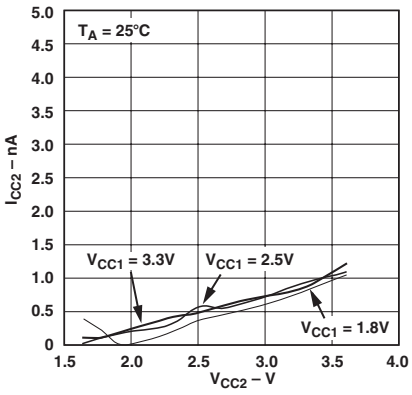
CAUTION

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although the ADG3232 features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.

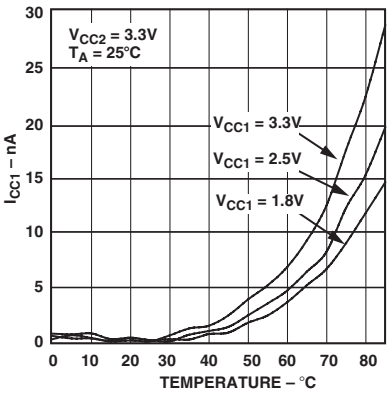
ADG3232–Typical Performance Characteristics



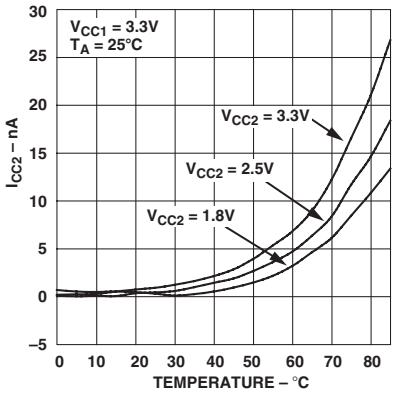
TPC 1. I_{CC1} vs. V_{CC1}



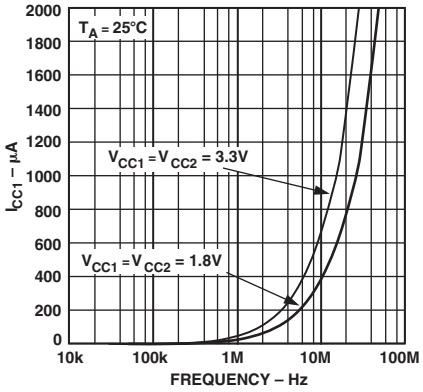
TPC 2. I_{CC2} vs. V_{CC2}



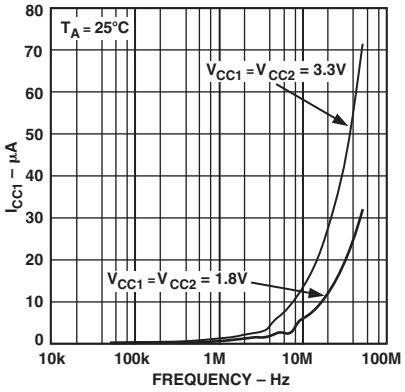
TPC 3. I_{CC1} vs. Temperature



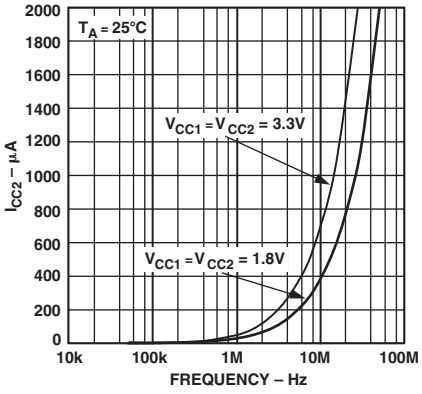
TPC 4. I_{CC2} vs. Temperature



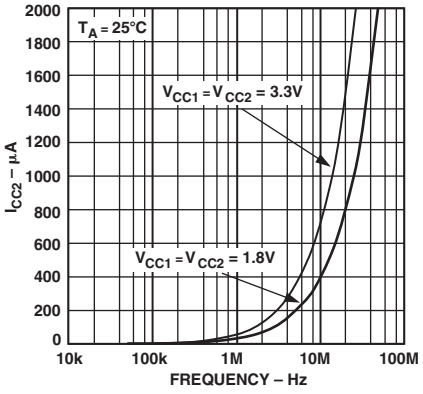
TPC 5. I_{CC1} vs. Frequency, A1–Y



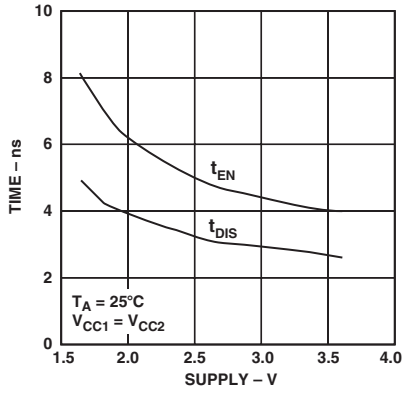
TPC 6. I_{CC1} vs. Frequency, A2–Y



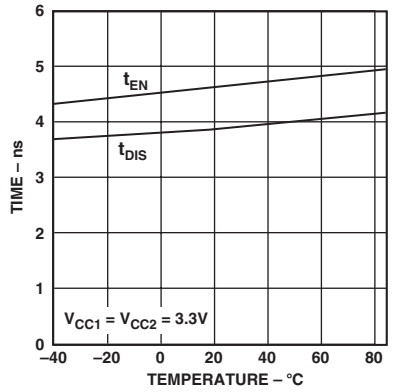
TPC 7. I_{CC2} vs. Frequency, A1–Y



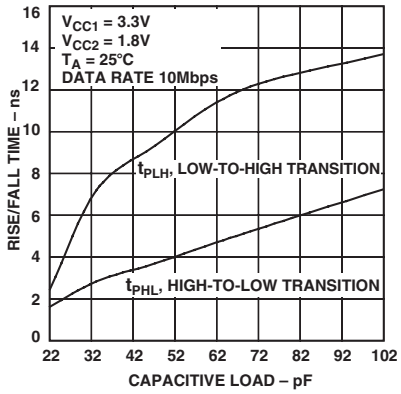
TPC 8. I_{CC2} vs. Frequency, A2–Y



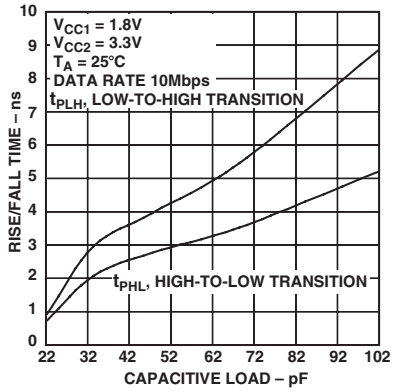
TPC 9. Enable, Disable Time vs. Supply



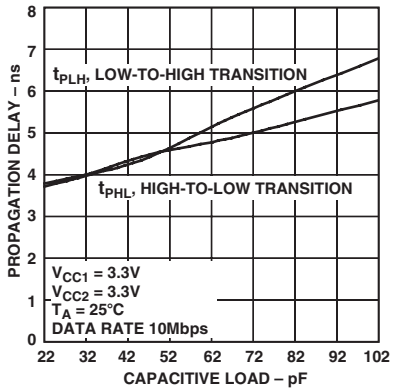
TPC 10. Enable, Disable Time vs. Temperature



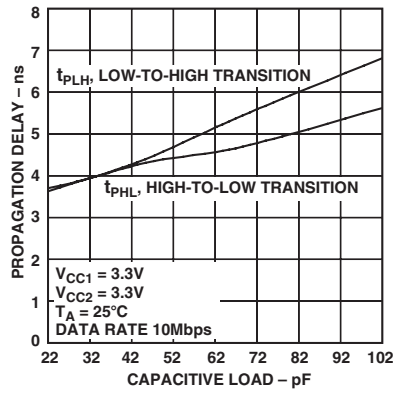
TPC 11. Rise/Fall Time vs. Capacitive Load, A1/A2–Y1



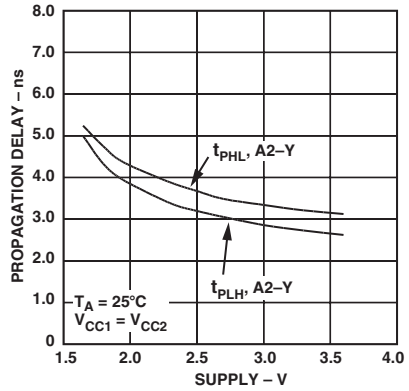
TPC 12. Rise/Fall Time vs. Capacitive Load, A1/A2–Y1



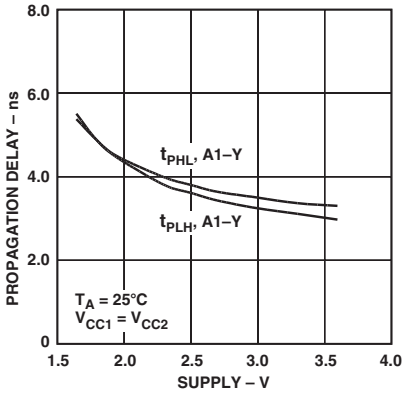
TPC 13. Propagation Delay vs. Capacitive Load, A2–Y



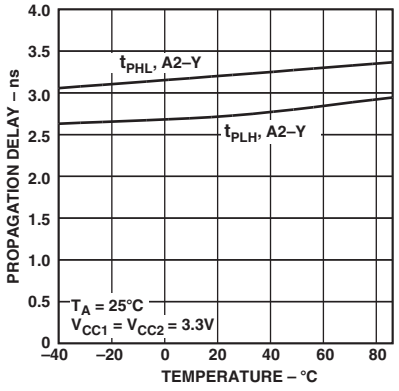
TPC 14. Propagation Delay vs. Capacitive Load, A1–Y



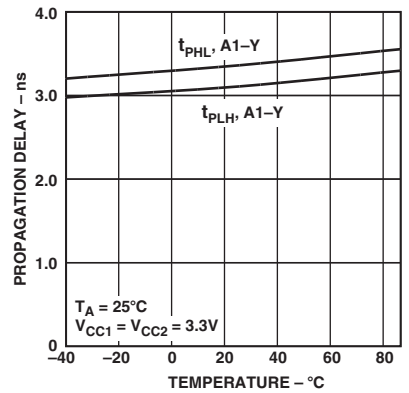
TPC 15. Propagation Delay vs. Supply



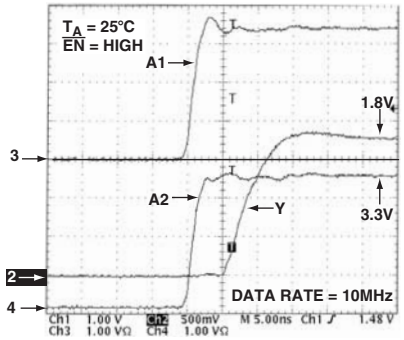
TPC 16. Propagation Delay vs. Supply, A1–Y



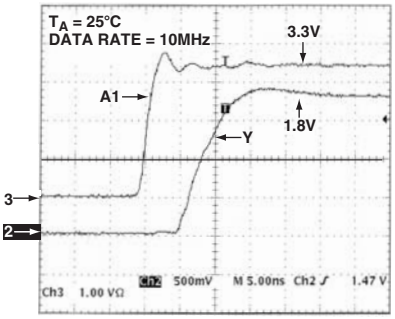
TPC 17. Propagation Delay vs. Temperature



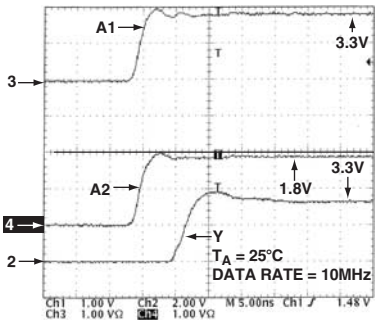
TPC 18. Propagation Delay vs. Temperature, A1–Y



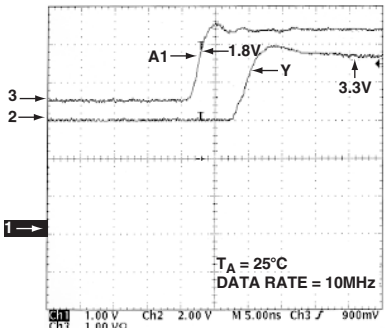
TPC 19. Input/Output V_{CC1} = 3.3 V, V_{CC2} = 1.8 V



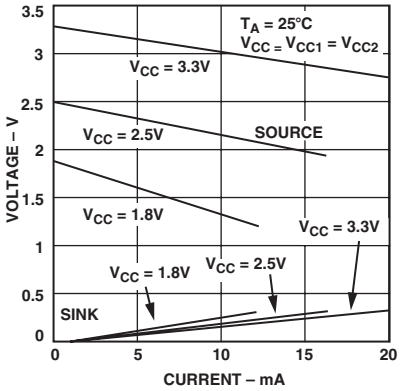
TPC 20. Input/Output V_{CC1} = 3.3 V, V_{CC2} = 1.8 V



TPC 21. Input/Output V_{CC1} = 1.8 V, V_{CC2} = 3.3 V



TPC 22. Input/Output V_{CC1} = 1.8 V, V_{CC2} = 3.3 V



TPC 23. Y Sink and Source Current

TEST CIRCUITS

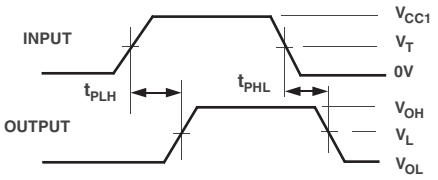


Figure 1. Propagation Delay

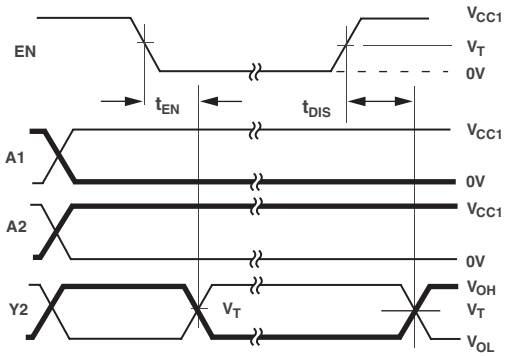


Figure 2. Enable and Disable Times

DESCRIPTION

The ADG3232 is a mux level translating device designed on a submicron process that operates from supplies as low as 1.65 V. The device is guaranteed for operation over the supply range 1.65 V to 3.6 V. It operates from two supply voltages, allowing bidirectional level translation i.e., it translates lower voltages to higher voltages and vice versa. The signal path is unidirectional, meaning data may only flow from A to Z.

A1 and $\overline{EN}$ Input

The A1 and enable ($\overline{EN}$) inputs have V_{IL}/V_{IH} logic levels so that the part can accept logic levels of V_{OL}/V_{OH} independent of the value of the supply being used. Both these inputs (A1 and $\overline{EN}$) are capable of accepting inputs outside the V_{CC1} supply range. There are no internal diodes to the supply rails on these pins, so they can handle inputs above the supply but inside the absolute maximum ratings.

Operation

Figure 3 shows the ADG3232 in a typical application; the signal paths are from A1 or A2 to Y. The device will level translate the signal applied to A1/A2 from a V_{CC1} logic level (this level translation can be either to a higher or a lower supply) and route the signal to the Y output, which will have standard V_{OL}/V_{OH} levels for V_{CC2} supplies.

The supplies in Figure 3 may be any combination of supplies, e.g., V_{CC1} and V_{CC2} may be anywhere in the 1.65 V to 3.6 V range.

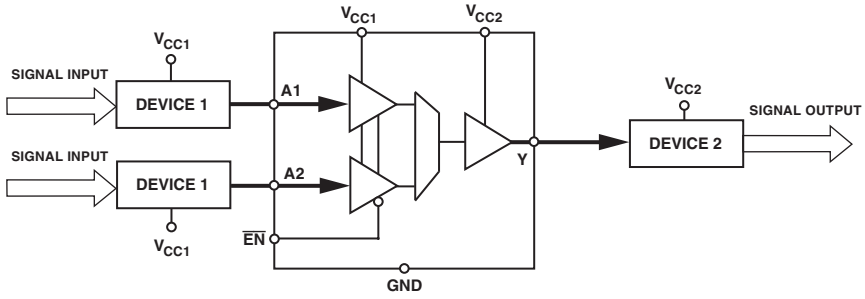
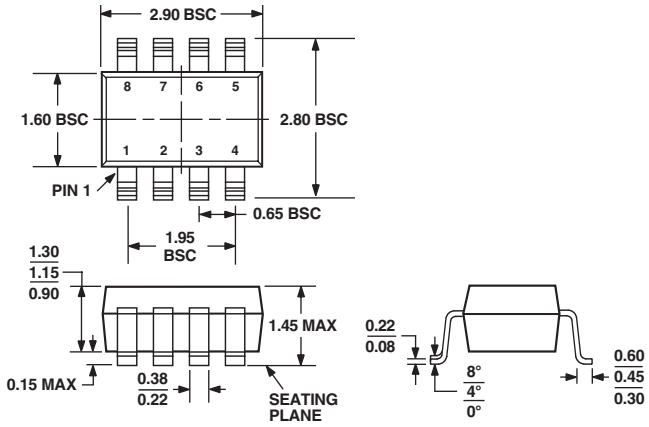


Figure 3. Typical Operation of the ADG3232 Level Translating Switch

OUTLINE DIMENSIONS

8-Lead Small Outline Transistor Package [SOT-23]
(RJ-8)
Dimensions shown in millimeters



COMPLIANT TO JEDEC STANDARDS MO-178BA

C03299–0–5/03(0)